



Material Content Data Sheet



Sales Product Name		IPA90R1K2C3		Issued		29. August 2013			
MA#		MA000468308							
Package		PG-TO220-3-111		Weight*		2240.66 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	4.798	0.21	0.21	2141	2141	
leadframe	non noble metal	iron	7439-89-6	1.120	0.05		500		
	inorganic material	phosphorus	7723-14-0	0.336	0.02		150		
	non noble metal	copper	7440-50-8	1118.332	49.92	49.99	499107	499757	
wire	non noble metal	aluminium	7429-90-5	0.780	0.03	0.03	348	348	
encapsulation	organic material	carbon black	1333-86-4	2.209	0.10		986		
	plastics	epoxy resin	-	207.614	9.27		92657		
	inorganic material	silicondioxide	60676-86-0	894.507	39.92	49.29	399215	492858	
leadfinish	non noble metal	tin	7440-31-5	7.942	0.35	0.35	3544	3544	
plating	non noble metal	nickel	7440-02-0	0.305	0.01		136		
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.01	0	136	
solder	non noble metal	antimony	7440-36-0	0.272	0.01		122		
	noble metal	silver	7440-22-4	0.681	0.03		304		
	non noble metal	tin	7440-31-5	1.770	0.08	0.12	790	1216	
*deviation	< 10%					Sum in total:	100.00		1000000

Important Remarks:

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